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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of: : Docket: YOR919990336US2

Chao-kun Hu et al. : Prior Group Art Unit: 2815

Serial No.: To be Assigned : Prior Examiner: A. Wilson

Filed: Herewith : Date: November 13, 2001

For: REDUCED ELECTROMIGRATION AND STRESSED INDUCED MIGRATION

OF Cu WIRES BY SURFACE COATING

Preliminary Amendment

Commissioner for Patents Washington, D.C. 20231

Sir:

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In the Specification

Please replace Equation 1 at page 3, line 19, with the following rewritten equation 1:

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 $Cu + Pd^{++} \rightarrow Cu^{++} + Pd$

Please replace Equation 2 at page 4, line 5, with the following rewritten equation 2:

(1)

A2

reducing agent + Me^{n+} + Cu \rightarrow Cu/Me + oxidized form of reducing agent (2)

Please replace Equation 3 at page 4, line 9, with the following rewritten equation 3:

A3

 $2 H_2 PO_2^{-} + C_0^{2+} + H_2 0... ((..Cu..)) \rightarrow C_0 + 2HPO_3^{2-} + H_2^{2-} + 4 H^+$ (3)

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